

FOR IMMEDIATE RELEASE

Tekelec Joins HDP User Group International

Scottsdale, Ariz., June 11, 2007—The High Density Packaging User Group International, Inc. (HDP), a global non-profit cooperative research and development organization for the telecommunications and computer industries, announced that Tekelec has joined the organization as a corporate member.

“Tekelec brings a wealth of knowledge and experience to HDP, and the company’s support will be beneficial to current and future projects,” said Marshall Andrews, executive director of HDP. “Tekelec is an active contributor to our SAC Reliability—Mild Acceleration Project. The HDP organization and its member companies welcome Tekelec as one of our newest members.”

John Thacker, director, Hardware Engineering, Tekelec, added, “On behalf of the Tekelec management team, we are pleased to participate in the HDP User Group Consortium. Specific bans on the use of hazardous materials have required manufacturers like Tekelec to find reliable replacement materials. A viable alternative is lead-free solder, which has been extremely valuable to many companies with manufacturing operations, especially those in telecommunications. Participation in the Mild Acceleration Project has helped us at Tekelec understand what steps are required to transition to the use of reliable lead-free products.”

About Tekelec.

Tekelec is a high-performance network applications company that is accelerating the transition to IP Multimedia Subsystem (IMS) networks for service providers around the globe. With its unparalleled experience at the intersection of network applications and session control, Tekelec creates the most-efficient platforms for managing media and delivering network solutions. Corporate headquarters are located in Morrisville, N.C., U.S.A., with research and development facilities and sales offices throughout the world.

About the HDP User Group International Inc.

HDP User Group (www.hdpug.org) is a global research and development organization based in Scottsdale AZ, dedicated to “reducing the costs and risks for the Telecommunications and Computer industries when using advanced electronic packaging and assembly”. This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP maintains additional offices in Austin, Texas; Stockholm, Sweden; and Tokyo, Japan.

For more information, visit HDP User Group on the Internet at www.hdpug.org or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963.

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